Zener diode

Features

1. Micro Melf package, saving space
2. Fits onto SOD 323/SOT 23 footprints

Applications

Voltage stabilization

Absolute Maximum Ratings

T_j=25 ℃

Parameter	Test Conditions	Type	Symbol	Value	Unit
Power dissipation	$R_{thJA} \leqq 300K╱W$		P_V	500	mW
Z-current			I_Z	P_V/V_Z	mA
Junction temperature			T_j	175	℃
Storage temperature range			T_{stg}	-65~+175	℃

Stresses exceeding maximum ratings may damage the device. Maximum ratings are stress ratings only. Functional operation above the recommended operating conditions is not implied. Extended exposure to stresses above the recommended operating conditions may affect device reliability.

Electrical Characteristics

T_j=25 ℃

Parameter	Test Conditions	Type	Symbol	Min	Typ	Max	Unit
Forward voltage	I_F=200mA		V_F			1.5	V

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Type	V_{Znom}	I_{ZT}	for V_{ZT} and	r_{ziT}	r_{ziK} at	I_{ZK}	I_R and	I_R at	V_R	TK_{VZ}
BZM55B.	V	mA	V	Ω	Ω	mA	µA	µA[1]	V	%/K
2V0	2.0	5	1.96~2.04	100	<600	1	<150	<300	1	-0.09~-0.06
2V2	2.2	5	2.15~2.25	100	<600	1	<150	<300	1	-0.09~-0.06
2V4	2.4	5	2.35~2.45	<85	<600	1	<50	<100	1	-0.09~-0.06
2V7	2.7	5	2.64~2.76	<85	<600	1	<10	<50	1	-0.09~-0.06
3V0	3.0	5	2.94~3.06	<85	<600	1	<4	<40	1	-0.08~-0.05
3V3	3.3	5	3.24~3.36	<85	<600	1	<2	<40	1	-0.08~-0.05
3V6	3.6	5	3.52~3.68	<85	<600	1	<2	<40	1	-0.08~-0.05
3V9	3.9	5	3.82~3.98	<85	<600	1	<2	<40	1	-0.08~-0.05
4V3	4.3	5	4.22~4.38	<75	<600	1	<1	<20	1	-0.06~-0.03
4V7	4.7	5	4.6~4.8	<60	<600	1	<0.5	<10	1	-0.05~+0.02
5V1	5.1	5	5.0~5.2	<35	<550	1	<0.1	<2	1	-0.02~+0.02
5V6	5.6	5	5.48~5.72	<25	<450	1	<0.1	<2	1	-0.05~+0.05
6V2	6.2	5	6.08~6.32	<10	<200	1	<0.1	<2	2	0.03~0.06
6V8	6.8	5	6.66~6.94	<8	<150	1	<0.1	<2	3	0.03~0.07
7V5	7.5	5	7.35~7.65	<7	<50	1	<0.1	<2	5	0.03~0.07
8V2	8.2	5	8.04~8.36	<7	<50	1	<0.1	<2	6.2	0.03~0.08
9V1	9.1	5	8.92~9.28	<10	<50	1	<0.1	<2	6.8	0.03~0.09
10	10	5	9.8~10.2	<15	<70	1	<0.1	<2	7.5	0.03~0.1
11	11	5	10.78~11.22	<20	<70	1	<0.1	<2	8.2	0.03~0.11
12	12	5	11.76~12.24	<20	<90	1	<0.1	<2	9.1	0.03~0.11
13	13	5	12.74~13.26	<26	<110	1	<0.1	<2	10	0.03~0.11
15	15	5	14.7~15.3	<30	<110	1	<0.1	<2	11	0.03~0.11
16	16	5	15.7~16.3	<40	<170	1	<0.1	<2	12	0.03~0.11
18	18	5	17.64~18.36	<50	<170	1	<0.1	<2	13	0.03~0.11
20	20	5	19.6~20.4	<55	<220	1	<0.1	<2	15	0.03~0.11
22	22	5	21.55~22.45	<55	<220	1	<0.1	<2	16	0.04~0.12
24	24	5	23.5~24.5	<80	<220	1	<0.1	<2	18	0.04~0.12
27	27	5	26.4~27.6	<80	<220	1	<0.1	<2	20	0.04~0.12
30	30	5	29.4~30.6	<80	<220	1	<0.1	<2	22	0.04~0.12
33	33	5	32.4~33.6	<80	<220	1	<0.1	<2	24	0.04~0.12
36	36	5	35.3~36.7	<80	<220	1	<0.1	<2	27	0.04~0.12
39	39	2.5	38.2~39.8	<90	<500	0.5	<0.1	<5	30	0.04~0.12
43	43	2.5	42.1~43.9	<90	<600	0.5	<0.1	<5	33	0.04~0.12
47	47	2.5	46.1~47.9	<110	<700	0.5	<0.1	<5	36	0.04~0.12
51	51	2.5	50~52	<125	<700	0.5	<0.1	<10	39	0.04~0.12
56	56	2.5	54.9~57.1	<135	<1000	0.5	<0.1	<10	43	0.04~0.12
62	62	2.5	60.8~63.2	<150	<1000	0.5	<0.1	<10	47	0.04~0.12
68	68	2.5	66.6~69.4	<200	<1000	0.5	<0.1	<10	51	0.04~0.12
75	75	2.5	73.5~76.5	<250	<1500	0.5	<0.1	<10	56	0.04~0.12

[1] at T_j=150℃

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Characteristics (T$_j$=25 °C unless otherwise specified)
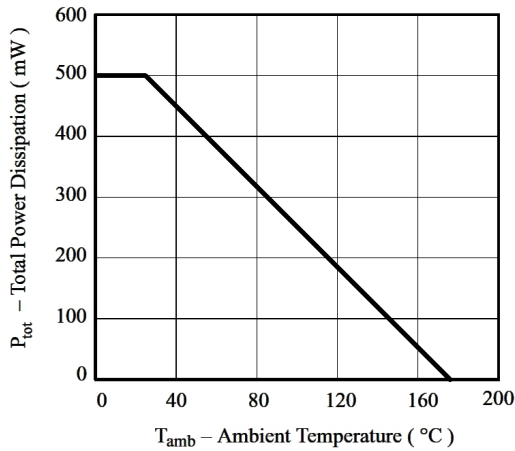

Figure 1. Total Power Dissipation vs. Ambient Temperature
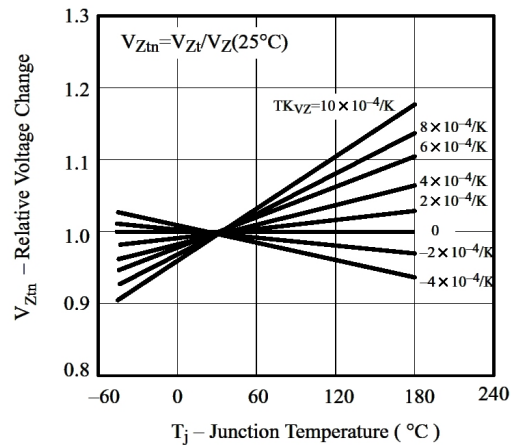

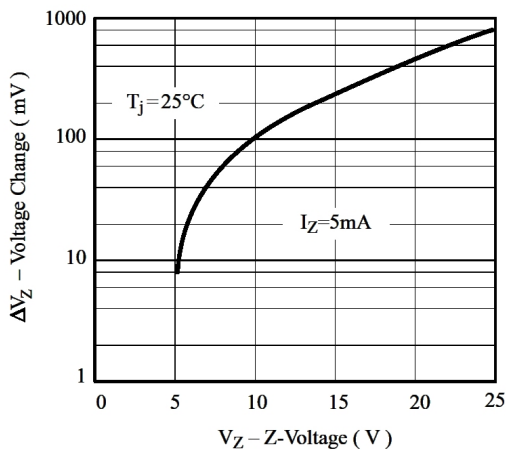**Figure 4. Typical Change of Working Voltage Vs. Junction Temperature**

Figure 2. Typical Change of Working Voltage under Operating Conditions at T$_{amb}$=25 °C

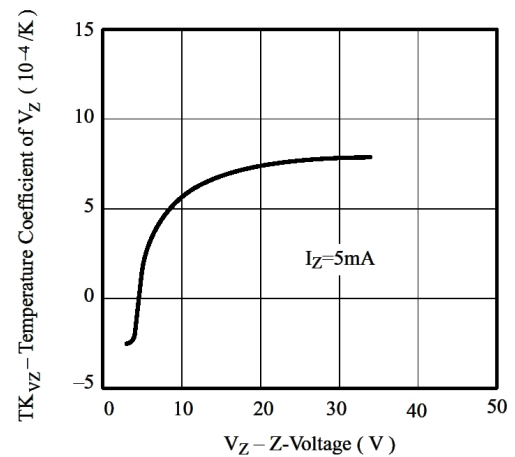**Figure 5. Temperature Coefficient of Vz vs. Z-Voltage**

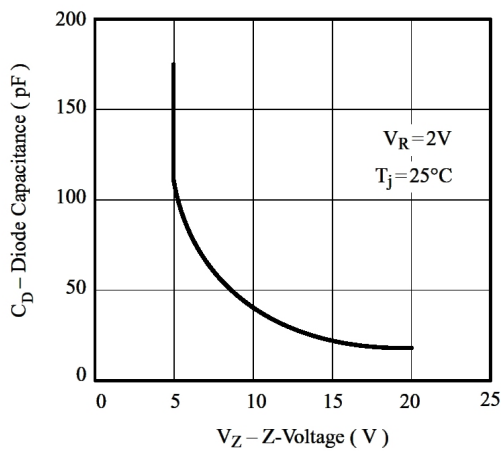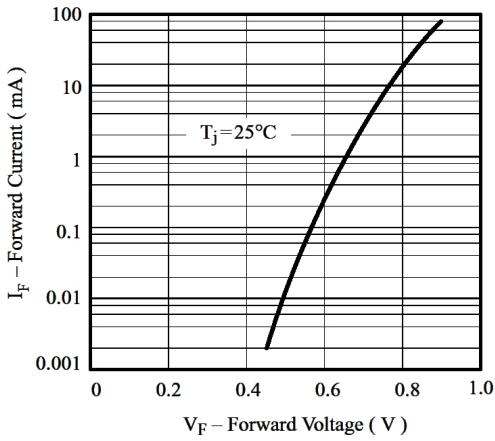**Figure 3. Diode Capacitance vs. Z-voltage**

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Figure 6. Forward Current vs. Forward Voltage
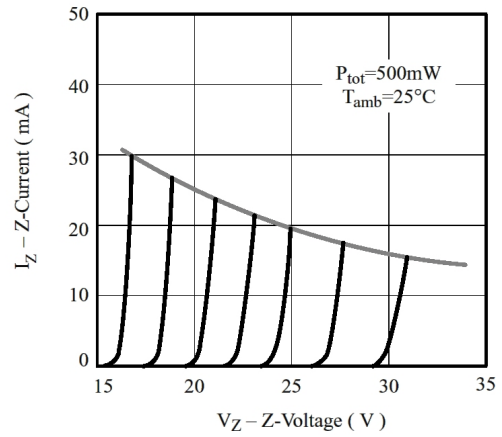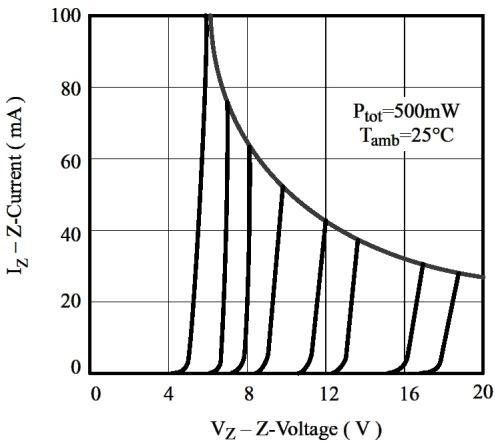

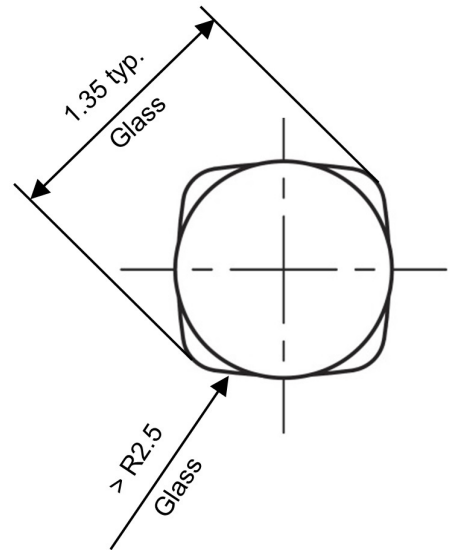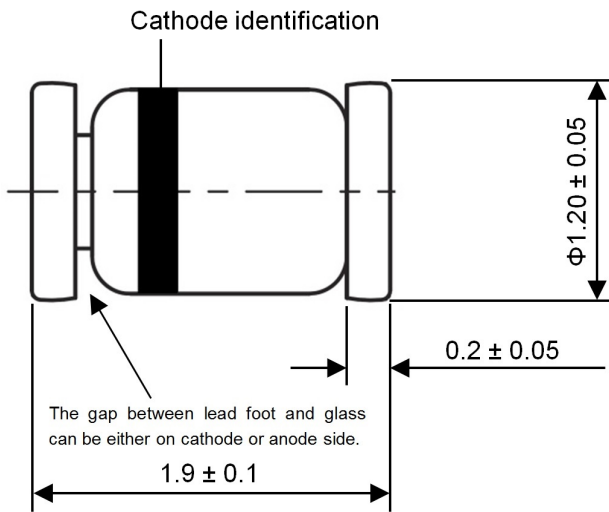**Figure 8. Z-Current vs. Z-Voltage**

Figure 7. Z-Current vs. Z-Voltage
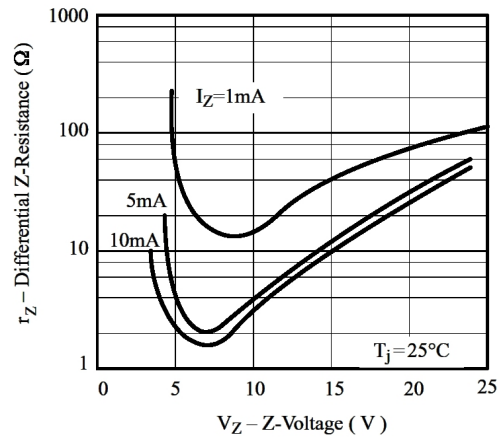
Figure 9. Differential Z-Resistance Vz vs. Z-Voltage

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Dimensions in mm

Cathode identification

Φ1.20 ± 0.05

0.2 ± 0.05

The gap between lead foot and glass can be either on cathode or anode side.

1.9 ± 0.1

Glass Case
Micro Melf

1.35 typ.
Glass

> R2.5
Glass

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